**Referenced Documents**

Procedure No. Document Description

[TA1041](file:///C%3A%5CUsers%5Cssteffan%5CAppData%5CLocal%5CMicrosoft%5CWindows%5CINetCache%5CContent.Outlook%5CAYGV4ML6%5CTA1041%20Precision%20Cleaning%20User%20Guide.docx) Precision Cleaning

[TA1288](file:///C%3A%5CUsers%5Cssteffan%5CAppData%5CLocal%5CMicrosoft%5CWindows%5CINetCache%5CContent.Outlook%5CAYGV4ML6%5CTA1288%20Ultrasonic%20Setup%20Procedure.docx) Ultrasonic cleaner Setup

[TA1287](file:///C%3A%5CUsers%5Cssteffan%5CAppData%5CLocal%5CMicrosoft%5CWindows%5CINetCache%5CContent.Outlook%5CAYGV4ML6%5CTA1287%20Special%20Requirements%20for%20Cleanroom%20PFT%20Area.docx) Special Requirement for Cleanroom

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GENERAL INCOMING CLEANING

* + Anything entering the cleanroom that is larger than a credit card must be wiped down per procedure TA1041 Process G to reduce contaminants brought into the room.
	+ Examples include, but are not limited to:
		- Job Boxes
		- Waffle packs
		- Part bags: Clear sealed, Pink reseal able, Silver ESD, etc.
		- Equipment
	+ It is not necessary to wipe down sensor sub-assemblies that are contained within a clean bag or container (including pink bags) unless it is going into the ISO7 cleanroom.

PRODUCT / PART CLEANING

* + Parts contained within a cleanroom heat sealed bag do not need to be cleaned (clean package per above).
	+ Product contaminants must be removed per the instruction below.
	+ **All information below is unless otherwise specified in router.**

CRYSTALS, ELECTRODES, DIAPHRAGMS

Thin or fragile parts must be cleaned per procedure TA1041 Process C, taking care to assure that parts are not damaged. Do not wash diaphragms with crystals or electrodes.

\*\*Do not wash crystals with marker / indelible ink.

* + These parts can be identified by:
		- The description “Xtal”, “Electrode”, “Diaphragm”.
		- Electrodes and Diaphragms are generally very thin.
		- Crystals generally have some type of polarity mark.

RAW PARTS

All incoming raw parts must be cleaned per procedure TA1041 Process A

* + These parts are the majority of the parts that we use.
	+ Examples include, but are not limited to:
		- Piston
		- Housings
		- Covers

COMPONENT SUB-ASSEMBLIES

Component Sub-assemblies must be cleaned per procedure TA1041 Process A.

* + These parts can be identified by identifying several parts assembled into one item.
	+ Care must be taken when these assemblies have exposed wires that can be damaged
	+ Examples include, but are not limited to:
		- Connectors
		- Charge pickup

SENSOR SUB-ASSEMBLIES, MAIN ASSEMBLIES, SENSOR ASSEMBLIES

Sensor Sub-Assemblies & Main Assemblies do not need to be cleaned, unless otherwise specified in router.

* + These parts can be identified by the description “Main Assembly”, “Subassembly”, “Element Assembly”, or by an item number that has 3-digits, a letter, and 2-3 digits (e.g. 123**A**123)
	+ Examples include, but are not limited to:
		- 40530-01 **ELEMENT** ASS'Y (POSITIVE P113B A GRADE))
		- 14907-01 Q-**EL**-COMP-POSITIVE-112A21
		- 21950-01 SENSOR SUBASSEMBLY-POS-20pF-109C11/C12

AMPLIFIERS & CIRCUIT BOARDS

Amplifiers and circuit boards do not need to be washed.

* + These parts can be identified by:
		- Part number: 12345-xxx-xx
		- The description “AMP” or “VAMP” or “QAMP”

ACCESSORY PARTS

All accessory parts do not need to be cleaned, unless otherwise specified in router.

* + These parts can be identified by:
		- No item number, or item number starting with F
		- Job usually will contain a finished sensor assembly.
	+ Examples include, but are not limited to:
		- Brass Seals
		- Clamp nuts
		- Kitted parts
		- Part numbers starting with:
			* 045B\_\_
			* 060A\_\_